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**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Ikuya MIYAZAWA

Application No.: 10/090,142

Docket No.: 112155

Filed: March 5, 2002

For: SOLDERING METHOD, SOLDERING DEVICE, AND METHOD AND DEVICE  
OF FABRICATING ELECTRONIC CIRCUIT MODULE

**REQUEST FOR CORRECTION OF PALM RECORDS**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

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JAO:JSA/cmm

Date: May 14, 2002

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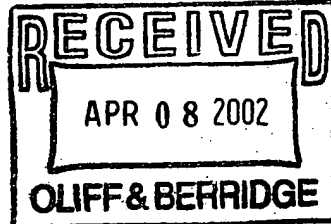
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| APPLICATION NUMBER | FILING DATE | GRP ART UNIT | FIL FEE REC'D | ATTY. DOCKET NO. | DRAWINGS | TOT CLAIMS | IND CLAIMS |
|--------------------|-------------|--------------|---------------|------------------|----------|------------|------------|
| 10/090,142         | 03/05/2002  | 1725         | 776           | 112155           | 5        | 22         | 2          |

CONFIRMATION NO. 5458

25944  
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## FILING RECEIPT



\*OC000000007796943\*

Date Mailed: 04/04/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

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## Assignment For Published Patent Application

SEIKO EPSON CORPORATION, Tokyo, JAPAN;

## Domestic Priority data as claimed by applicant

## Foreign Applications

JAPAN 2001-75534 03/16/2001

If Required, Foreign Filing License Granted 04/04/2002

Projected Publication Date: To Be Determined - pending completion of Missing Parts

Non-Publication Request: No

Early Publication Request: No

## Title

Soldering method, soldering device, and method and device of fabricating electronic circuit module

## Preliminary Class